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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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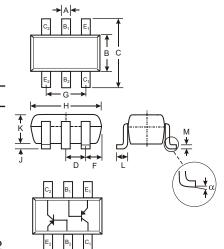
DUAL PNP SMALL SIGNAL SURFACE MOUNT TRANSISTOR

Features

- Epitaxial Planar Die Construction
- Ideal for Low Power Amplification and Switching
- Ultra-Small Surface Mount Package

Mechanical Data

- Case: SOT-363, Molded Plastic
- Case Material UL Flammability Rating Classification 94V-0
- Moisture sensitivity: Level 1 per J-STD-020A
- Terminals: Solderable per MIL-STD-202, Method 208
- Terminal Connections: See Diagram
- Marking (See Page 2): K3N
- Ordering & Date Code Information: See Page 2
- Weight: 0.006 grams (approx.)



SOT-363							
Dim	Min	Max					
Α	0.10	0.30					
В	1.15	1.35					
С	2.00 2.20						
D	0.65 N	0.65 Nominal					
F	0.30	0.40					
Н	1.80	2.20					
J	_	0.10					
K	0.90	1.00					
L	0.25	0.40					
М	0.10	0.25					
α	0°	8°					
All Dimensions in mm							

Maximum Ratings @ T_A = 25°C unless otherwise specified

Characteristic	Symbol	MMDT3906	Unit	
Collector-Base Voltage	V _{CBO}	-40	V	
Collector-Emitter Voltage	V _{CEO}	-40	V	
Emitter-Base Voltage	V _{EBO}	-5.0	V	
Collector Current - Continuous	Ic	-200	mA	
Power Dissipation (Note 1)	Pd	200	mW	
Thermal Resistance, Junction to Ambient	$R_{ heta JA}$	625	°C/W	
Operating and Storage and Temperature Range	T _j , T _{STG}	-55 to +150	°C	

Ordering Information (Note 2)

Device	Packaging	Shipping		
MMDT3906-7	SOT-363	3000/Tape & Reel		

Notes:

- 1. Device mounted on FR-4 PCB; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.
- 2. For Packaging Details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

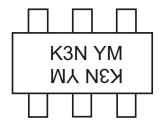


Electrical Characteristics @ T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 3)						
Collector-Base Breakdown Voltage	V _{(BR)CBO}	V _{(BR)CBO} -40		V	$I_C = -10\mu A, I_E = 0$	
Collector-Emitter Breakdown Voltage	V _{(BR)CEO}	-40	_	V	I _C = -1.0mA, I _B = 0	
Emitter-Base Breakdown Voltage	V _{(BR)EBO}	-5.0	_	V	$I_E = -10\mu A, I_C = 0$	
Collector Cutoff Current	I _{CEX}	_	-50	nA	$V_{CE} = -30V, V_{EB(OFF)} = -3.0V$	
Base Cutoff Current	I _{BL}	_	-50	nA	$V_{CE} = -30V, V_{EB(OFF)} = -3.0V$	
ON CHARACTERISTICS (Note 3)			•	•		
DC Current Gain	h _{FE}	60 80 100 60 30	300	_	I _C = -1.00μA, V _{CE} = -1.0V I _C = -1.0mA, V _{CE} = -1.0V I _C = -10mA, V _{CE} = -1.0V I _C = -50mA, V _{CE} = -1.0V I _C = -100mA, V _{CE} = -1.0V	
Collector-Emitter Saturation Voltage	V _{CE(SAT)}	_	-0.25 -0.40	V	$I_C = -10mA$, $I_B = -1.0mA$ $I_C = -50mA$, $I_B = -5.0mA$	
Base- Emitter Saturation Voltage	V _{BE(SAT)}	-0.65 —	-0.85 -0.95	V	$I_C = -10mA$, $I_B = -1.0mA$ $I_C = -50mA$, $I_B = -5.0mA$	
SMALL SIGNAL CHARACTERISTICS	•		•	•		
Output Capacitance	C _{obo}	_	4.5	pF	$V_{CB} = -5.0V$, $f = 1.0MHz$, $I_E = 0$	
Input Capacitance	C _{ibo}	_	10	pF	$V_{EB} = -0.5V$, $f = 1.0MHz$, $I_{C} = 0$	
Input Impedance	h _{ie}	2.0	12	kΩ		
Voltage Feedback Ratio	h _{re}	0.1	10	x 10 ⁻⁴	V _{CE} = 10V, I _C = 1.0mA,	
Small Signal Current Gain	h _{fe}	100	400	_	f = 1.0kHz	
Output Admittance	h _{oe}	3.0	60	μS		
Current Gain-Bandwidth Product	f⊤	250	_	MHz	$V_{CE} = -20V, I_{C} = -10mA,$ f = 100MHz	
Noise Figure	NF	_	4.0	dB	V_{CE} = -5.0V, I_{C} = -100 μ A, R_{S} = 1.0k Ω , f = 1.0kHz	
SWITCHING CHARACTERISTICS			•		•	
Delay Time	t _d	_	35	ns	V _{CC} = -3.0V, I _C = -10mA,	
Rise Time	t _r	_	35	ns	$V_{BE(off)} = 0.5V, I_{B1} = -1.0mA$	
Storage Time	ts	_	225	ns	$V_{CC} = -3.0V, I_{C} = -10mA,$	
Fall Time	t _f	_	75	ns	$I_{B1} = I_{B2} = -1.0 \text{mA}$	

Notes: 3. Short duration test pulse used to minimize self-heating.

Marking Information

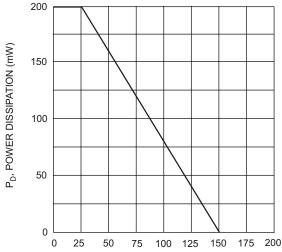


K3N = Product Type Marking Code YM = Date Code Marking Y = Year ex: N = 2002 M = Month ex: 9 = September

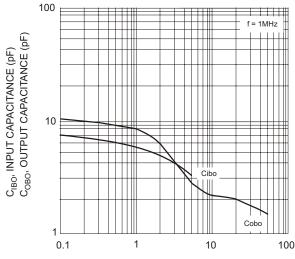
Date Code Key

Year	1998	1999	2000	2001	2002	2003	2004	2005	2006	2007	2008	2009
Code	J	K	L	М	N	Р	R	S	Т	U	V	W
Month	Jan	Feb	March	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D





T_A, AMBIENT TEMPERATURE (°C) Fig. 1, Max Power Dissipation vs Ambient Temperature



V_{CB}, COLLECTOR-BASE VOLTAGE (V) Fig. 2, Input and Output Capacitance vs. Collector-Base Voltage

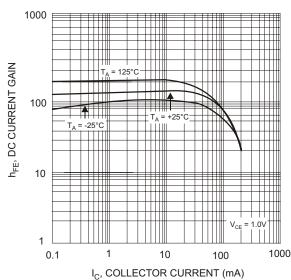
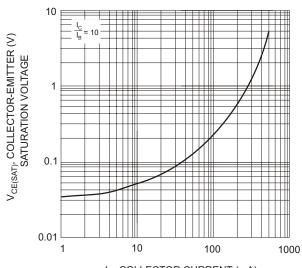
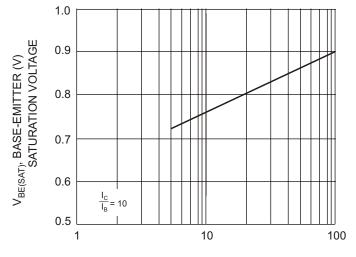


Fig. 3, Typical DC Current Gain vs Collector Current



I_C, COLLECTOR CURRENT (mA)
Fig. 4, Typical Collector-Emitter Saturation Voltage
vs. Collector Current



I_C, COLLECTOR CURRENT (mA)
Fig. 5, Typical Base-Emitter
Saturation Voltage vs. Collector Current